



Customer Information Notification

202308008I : MC33972 and MC33975 Data Sheet Updates (Technical Clarifications / Corrections)

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 07, 2023 **Effective date:** Sep 08, 2023

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Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input checked="" type="checkbox"/> Other: Data Sheet Update (Technical Clarifications / Corrections)			

PCN Overview

Description

NXP Semiconductors announces data sheet updates for the MC33972 and MC33975 (MSDI - Multiple Switch Detection Interface with Suppressed Wake-up) products associated with this notification. New MC33972 data sheet revision 20.0 and new MC33975 data sheet revision 12.0 are now available. Please see the revision history included in the updated documents for a detailed description of the changes.

**** Documentation update only - absolutely no change to product or materials ****

Correct the data sheet package drawing referenced to 98ASA00259D Rev B, which includes etched leadframe package representation.

New MC33972 revision 20.0 data sheet is attached to this notice and can be accessed at:

<https://www.nxp.com/docs/en/data-sheet/MC33972.pdf>

New MC33975 revision 12.0 data sheet is attached to this notice and can be accessed at:

<https://www.nxp.com/docs/en/data-sheet/MC33975.pdf>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The data sheets have been updated for technical clarifications and corrections - to correct the data sheet package drawing referenced to 98ASA00259D Rev B, which includes etched leadframe package representation.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

Related Notification

Notification	Issue Date	Effective Date	Title
202305031F01	May 25, 2023	Aug 23, 2023	SOIC 32LD Exposed Pad Stamped Leadframe Qualification

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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